DECLARATION

As a below named inventor, hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled DEVICE AND METHOD FOR PROTECTING AGAINST OXIDATION OF A CONDUCTIVE LAYER IN SAID DEVICE, the specification of which:

    _X_ is attached hereto.

    ___ was filed on _____, as Application Serial No. _____.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims.

I acknowledge the duty to disclose information which is material to patentability of the subject matter claimed in this application as "materiality" is defined in Title 37 of the Code of Federal Regulations, § 1.56.

I hereby claim the benefit of any earlier filing date in the United States to which I am entitled under Title 35 of the United States Code, § 120 and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35 of the United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37 of the Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(Application Serial No.)	(Filing Date)	(Status)

Send correspondence to:

> Charles B. Brantley, II, Mail Stop 525
> Micron Technology, Inc.
> 8000 S. Federal Way
> Boise, Idaho 83706
> (208) 368-4557

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first or sole inventor: [Vishnu K. Agarwal]

Inventor's Signature: _____

Date: 11 | 24 | 98   (First, Middle Initial, Last)

Residence Address: A303, 2382 E. Red Cedar Lane]

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